

Application No. 10/828556

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This listing of claim replaces all prior versions, and listings, of claims in the application:

1. (Currently Amended) A semiconductor device comprising:

a semiconductor chip;

a first wiring formed on an insulation film formed on a front surface of the semiconductor chip;

a second wiring formed on the insulation film;

a supporting body disposed on the front surface and having an opening to expose at least part of the second wiring;

an adhesive layer bonding the supporting body to the front surface; and

a third wiring disposed on an additional insulation film formed on a back surface of the semiconductor chip, extending along a side surface of the semiconductor chip, and connected to the first wiring,

wherein the supporting body does not cover any part of the back surface of the semiconductor substrate.

2. (Original) The semiconductor device of claim 1, further comprising a conductive terminal disposed on the third wiring.

3. (Original) The semiconductor device of claim 2, wherein the conductive terminal comprises a projecting electrode terminal.

4. (Original) The semiconductor device of claim 3, wherein the projecting electrode terminal is a solder bump or a gold bump.

5. (Currently Amended) A semiconductor device comprising:

a first semiconductor device comprising a first semiconductor chip, a first wiring formed on a front surface of the first semiconductor chip, a second wiring formed on the front surface, a supporting body ~~bonded to~~ disposed on the front surface and having an opening to expose at least part of the second wiring, an adhesive layer bonding the supporting body to the front surface, and

a third wiring disposed on a back surface of the semiconductor chip, extending along a side surface of the semiconductor chip and connected to the first wiring, the supporting body not covering any part of the back surface of the semiconductor substrate; and

a second semiconductor device disposed on the first semiconductor device, the second semiconductor device comprising a second semiconductor chip and a conductive terminal that is formed on a back surface of the second semiconductor chip and is connected to the second wiring of the first semiconductor device through the opening of the supporting body.

6. (Original) The semiconductor device of claim 5, further comprising a conductive terminal disposed on the third wiring.

7. (Original) The semiconductor device of claim 6, wherein the conductive terminal comprises a projecting electrode terminal.

8. (Original) The semiconductor device of claim 7, wherein the projecting electrode terminal is a solder bump or a gold bump.

CLAIMS 9-15(CANCELLED)

16. (New) A semiconductor device comprising:

a semiconductor chip;

a first wiring formed on an insulation film formed on a front surface of the semiconductor chip;

a second wiring formed on the insulation film;

a flat plate disposed on the front surface and having an opening to expose at least part of the second wiring;

an adhesive layer bonding the flat plate to the front surface; and

a third wiring disposed on an additional insulation film formed on a back surface of the semiconductor chip, extending along a side surface of the semiconductor chip, and connected to the first wiring.